

# MA3D756 (MA7D56)

Silicon epitaxial planar type (cathode common)

For switching mode power supply

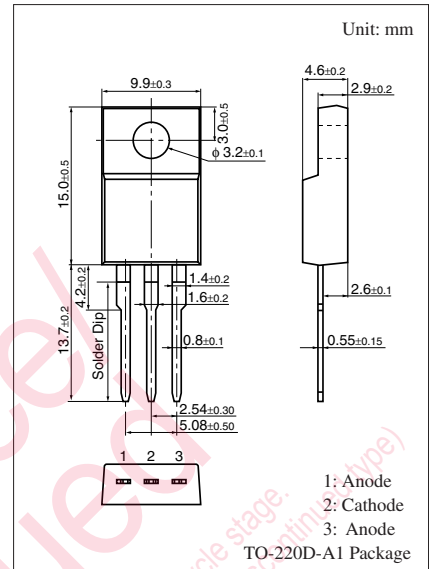
## ■ Features

- Low forward voltage  $V_F$
- High dielectric breakdown voltage: > 5 kV
- Easy-to-mount, due to its V cut lead end

## ■ Absolute Maximum Ratings $T_C = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Repetitive peak reverse voltage	$V_{RRM}$	60	V
Forward current (Average)	$I_{F(AV)}$	10	A
Non-repetitive peak forward surge current *	$I_{FSM}$	120	A
Junction temperature	$T_j$	-40 to +125	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-40 to +125	$^\circ\text{C}$

Note) \*: Half sine wave; 10 ms/cycle



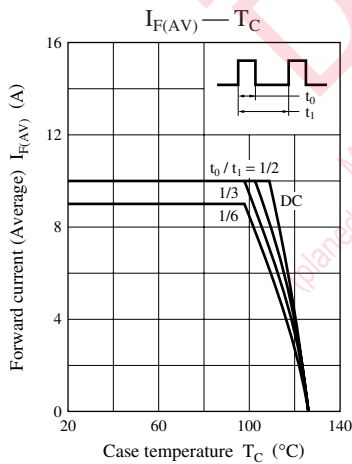
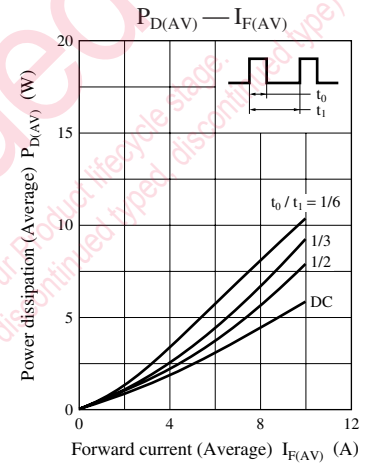
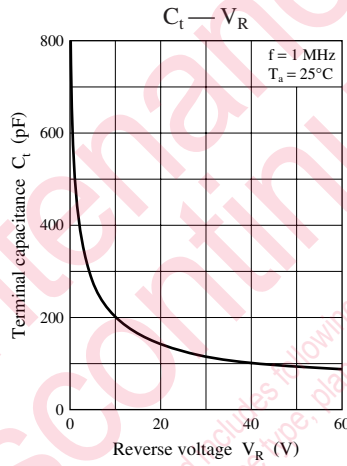
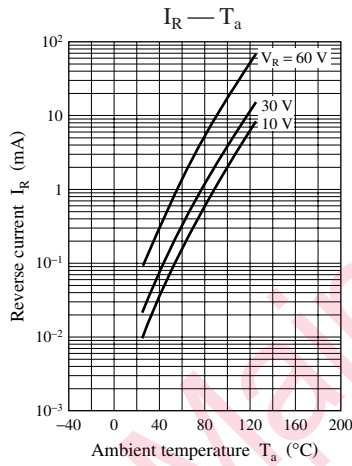
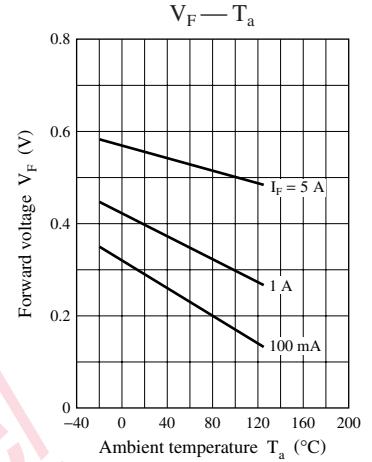
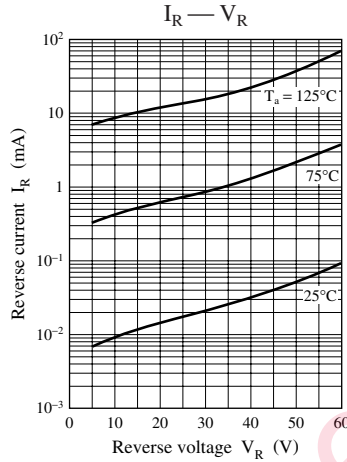
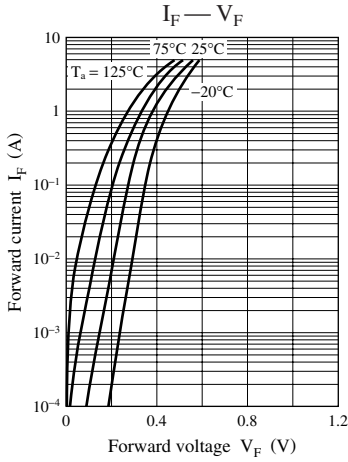
## ■ Electrical Characteristics $T_C = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	$V_F$	$I_F = 5 \text{ A}$			0.58	V
Reverse current	$I_R$	$V_R = 60 \text{ V}$			3	mA
Thermal resistance (j-c)	$R_{th(j-c)}$				3.0	$^\circ\text{C/W}$

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 50 MHz.

Note) The part number in the parenthesis shows conventional part number.



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